

## ABSTRACT

An object of the present invention is to provide a sheet-form thermosetting resin composition for sealing an electronic component, which meets the flame retardancy regulation (UL94V-0) and has excellent strength after curing. An object of the present invention is to provide a highly reliable resin-sealed semiconductor device. An object of the present invention is to provide a method of manufacturing the resin-sealed semiconductor device. An aspect of the present invention relates to a sheet-form thermosetting resin composition for sealing an electronic component, having specific amount of silica ;meeting the flame retardancy regulation (UL94V-0) ; and having a three-point bending strength of 80 MPa or more at normal temperature after the resin composition is cured under heating at 150°C for 1 hour.